

TWEP-24

Topical Workshop on Electronics for Particle Physics
Glasgow, United Kingdom, 30 September – 4 October 2024



Workshop organization & venue



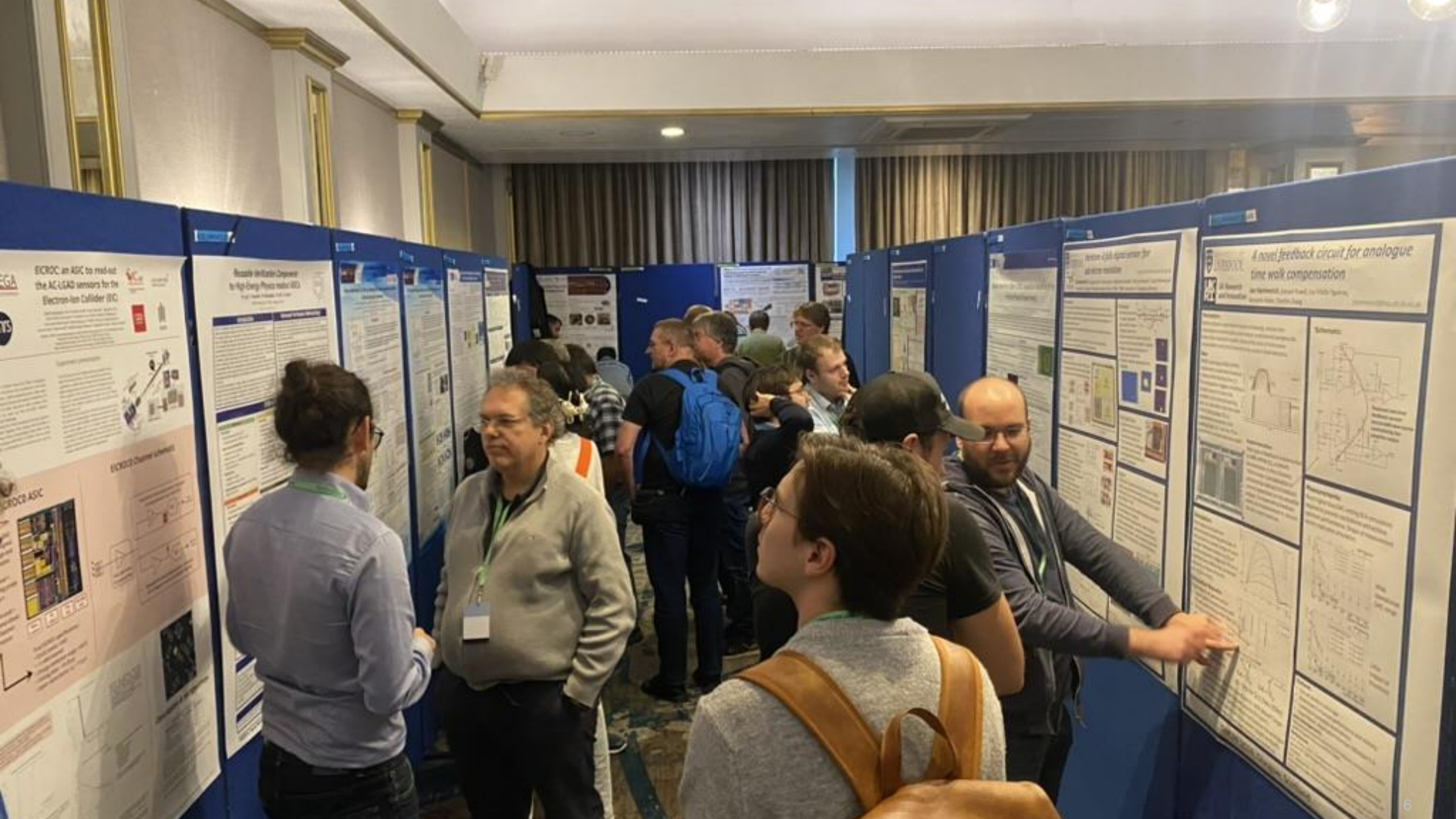




Case Trigger Cluster Finding

The slide content is partially obscured but appears to include a table with columns for "Case ID", "Date", "Location", and "Status".

Case ID	Date	Location	Status
1	2023-01-15	Room 101	Open
2	2023-01-16	Room 102	Open
3	2023-01-17	Room 103	Open
4	2023-01-18	Room 104	Open
5	2023-01-19	Room 105	Open
6	2023-01-20	Room 106	Open
7	2023-01-21	Room 107	Open
8	2023-01-22	Room 108	Open
9	2023-01-23	Room 109	Open
10	2023-01-24	Room 110	Open



ECROC an ASIC to read-out the ACUSAD sensors for the Electron-Ion Collider (EIC)

ECROC is a custom-designed ASIC for the ACUSAD sensors. It provides a high-resolution, low-noise readout of the sensor signals. The chip is fabricated in a 65nm CMOS technology and is designed to be compact and power-efficient. It is currently being tested in a laboratory setting and is expected to be used in the EIC experiment.

ECROC ASIC



The image shows a photograph of the ECROC ASIC chip and a block diagram of its internal structure. The chip is a small, square integrated circuit. The block diagram illustrates the various functional blocks and their interconnections within the ASIC.

Resistive Memory Crossbar for High Energy Physics detector ASIC

This poster discusses the design and implementation of a resistive memory crossbar for use in high energy physics detector ASICs. The crossbar architecture provides a high density of memory cells and is well-suited for the large data volumes generated by these detectors. The design is based on a 1T1R (1T1R) crossbar structure and is implemented in a 65nm CMOS technology.

High Resolution ADC for the EIC

This poster describes a high-resolution ADC designed for the Electron-Ion Collider (EIC). The ADC is based on a novel architecture that provides a high resolution and a wide dynamic range. It is currently being tested in a laboratory setting and is expected to be used in the EIC experiment.

ASIC for the EIC

This poster discusses the design and implementation of an ASIC for the Electron-Ion Collider (EIC). The ASIC is a custom-designed chip that provides a high-resolution, low-noise readout of the sensor signals. It is currently being tested in a laboratory setting and is expected to be used in the EIC experiment.

ASIC for the EIC

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A novel feedback circuit for analogue time walk compensation

This poster describes a novel feedback circuit for analogue time walk compensation. The circuit is designed to provide a high-resolution, low-noise readout of the sensor signals. It is currently being tested in a laboratory setting and is expected to be used in the EIC experiment.



The image shows a schematic diagram of the feedback circuit. The diagram illustrates the various components and their interconnections within the circuit. It includes a feedback loop, a comparator, and a DAC. The circuit is designed to provide a high-resolution, low-noise readout of the sensor signals.



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Geography

- % of UK landmass
- 790 islands
- Space - 10% of UK population
- Highland Boundary Fault
- Munros & Lichs
- Central Belt - Flatter & peopled
- Natural Resources



Overview

- I was invited to give a talk on 70 years of CERN electronics – but why?
 - I am not an historian, or an electronics engineer, but just old (enough?)
- Nevertheless, the subject was tempting.
 - I have tried to select some relevant material BUT
 - No claim to be a rigorous historical account with all contributors properly cited
 - this is potentially a huge subject impossible to do full justice to
 - I include some material I am familiar with and omit others
 - especially e.g. power supplies, specialist accelerator systems, computing...
- Declaration of interest
 - Now, many years of involvement in this area, mainly for the CMS experiment
 - But I am not an electronic designer or even, any longer, a hands-on user
 - despite that I seem to have dipped my toes in a lot of (hot, sometimes) water
 - Heavily involved in LEB, LERC, LECC, TWEPP for many years...

Expect some opinions – which you may not share

TWEPP October 2024

© H4

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Future Circular Collider, FCC

Inspired by successful LEP – LHC program at CERN
Comprehensive long-term program maximizing physics opportunities

A new 91km tunnel, 100 – 300 m underground
8 surface sites



Collider program:
FCC-ee: Luminosity frontier: 91, 160, 240, 365 GeV
FCC-hh: Energy frontier: 100 TeV

E. Gschwendtner, CERN



Quantum Technology for Sensing & Timing Applications

Prof Douglas J. Paul
Royal Academy of Engineering Chair in Emerging Technologies

780 nm DFB laser

Integrated DFB lasers

MEMS cells

MEMS resonators

Ge on Si Mid-infrared Photonics

Si Nanowire SEI

Ge on Si SPADs

Single Photon LIDAR





THE TRIPLE DISTILLED
AUCHENTOSHAN
SINGLE MALT SCOTCH WHISKY

THE TRIPLE DISTILLED
AUCHENTOSHAN
SINGLE MALT SCOTCH WHISKY











← Scotland's Wildlife
Environment Discovery Centre

Looking at Art
Art Discovery Centre →









Local organisation

- R. Bates (University of Glasgow, UK)
- A. Blue (University of Glasgow, UK)
- D. Maneuski (University of Glasgow, UK)
- S. Naik (University of Glasgow, UK)
- K. Walkingshaw Pass (University of Glasgow, UK)

Scientific organisation

- A. Kluge (CERN, CH, Chair)
- J. Alme (UIB, NO)
- S. Baron (CERN, CH)
- R. Bates (University of Glasgow, UK)
- A. Boccardi (CERN, CH)
- H. Chen (BNL, US)
- S. Danzeca (CERN, CH)
- C. Fernandez Bedoya (CIEMAT, ES)
- M. French (RAL, UK)
- D. Gascon (UB, ES)
- P. Gui (SMU, US)
- M. Hansen (CERN, CH)
- C. G. Hu (IPHC-IN2P3, FR)
- G. Lehmann Miotto (CERN, CH)
- D. Maneuski (University of Glasgow, UK)
- A. Ricci (CERN, CH, Secretary)
- A. Rivetti (INFN, IT)
- W. Snoeys (CERN, CH)
- F. Vasey (CERN, CH)
- K. Wyllie (CERN, CH)





Tutorial

- **Cadence**

- **Signal integrity optimisation**

- via simulation of the integrated circuit, PCB, connector, cable and system level
 - Electrical thermal co-simulation at PCB/IC package level
 - Optimisation of EMC at PCB/IC package level
 - Design of robust power supply network at PCB/IC package level
 - Simulation of DDR routing at PCB/IC package level
 - Simulation of High-Speed serial link routing at PCB/IC package level
 - Analysis of a complete system – PCB/package/connector/cable
- <https://indico.cern.ch/event/1381495/page/32655-tutorial>
- **If you are interested but have not registered, please tell us now**

Oral Presentation award

- Oral presentation award
- Friday, October 4, 11:10
- Referees
 - TWEPP scientific committee

Topical Workshop on Electronics
for Particle Physics
TWEPP-22

Oral Presentation Award

Presentation title

Presenter: Name

University of Zeiselmauer, Austria

Alexander Kluge

Scientific
Committee Chair



23 September
2022

- 15 Optimized Rad-Hard DC/DC Converters for HEP Applications
- 20 Yield Characterisation and Failure Analysis of the Monolithic Stitched Sensor MOSS for ALICE ITS3
- 34 Next generation fully integrated DCDC converters for HEP applications in 28nm technology
- 46 3D Integration of Pixel Readout Chips using Through-Silicon-Vias
- 56 Power distribution over the wafer-scale monolithic pixel detector - MOSAIX for ALICE ITS3
- 63 Silicon Photonics Circuits for the optical readout of CERN detectors
- 71 Performance tests and hardware qualification of the FEBs for the novel Super-Fine Grained Detector of T2K Phase II
- 112 The services chain for the upgrade of the Inner Tracker Pixel detector of the ATLAS experiment – full services from pixel modules to optical readout for the Outer Barrel sub-system
- 120 Development of the MOSAIX chip for the ALICE ITS3 upgrade
- 132 Applications of PixESL framework on pixel detectors for High Energy Physics experiments
- 135 Development of a novel low-mass module flex PCB using nano-wire-based flip-chip interconnection
- 165 Technical challenges designing a prototype common readout board for LHCb future upgrades
- 172 Design and characterization of the monolithic ASIC for the pre-shower upgrade of the FASER experiment

Proceedings

- Describe specifications and implementation challenges arising from these specifications
- Use quantitative (numbers) statements, comparisons and performance figures
 - and do not give statements that a given parameter needs to be high or low
- Limit introduction to relevant information to work you describe in the paper
 - Repetition of standards phrases about the LHC luminosity upgrade might only be useful if information is set in direct context to your work
- Describe work/challenge/complexity so that it can be understood by a scientist outside your field of competence
 - in contrast to writing an experiment collaboration note
- Describe why your work is worth being presented at a scientific/technical workshop
- Describe challenges/difficulties during implementation and how they were solved or why not
- Check quality of formatting, language, style and length

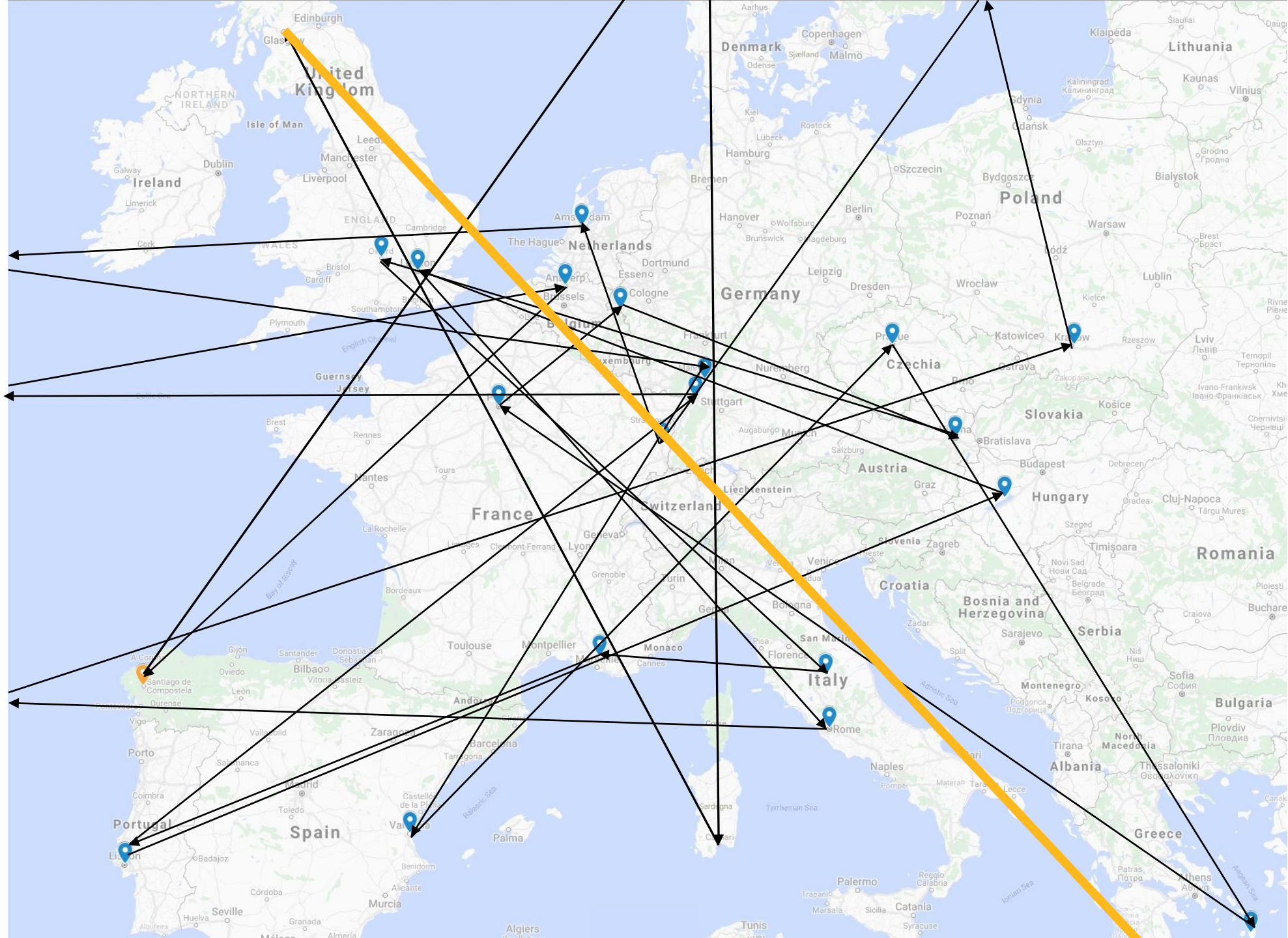
- **JINST** - <https://jinst.sissa.it/jinst/>
 - submission using JINST web based infra structure
 - organized as non-open access, no cost for author
 - JINST offers open access, cost would need to be covered by author/institute/experiment
 - or author institute has agreement with JINST
 - each paper assigned to 2 referees
 - from TWEPP scientific committee
- **Length**
 - number of pages must not exceed 5 pages
 - (excluding the title & abstract page & references) for both oral and poster contributions
- **Deadline November 3, 2024, 23:59 CET** → [no extension](#)
- **Instruction to authors**
 - TWEPP web page
 - <https://indico.cern.ch/event/1255624/page/28781-proceedings-instruction-for-authors>
 - review will be strict
 - 2 rounds of review
 - do not waste 1 round with insufficient formatting, structure, writing style or length

Questionnaire



- <https://indico.cern.ch/event/1381495/manage/surveys/5175/questionnaire/>

TWEPP25





United Kingdom

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Egypt

Sudan

Eritrea

Saudi Arabia

Yemen

Tunisia

Greece

Israel

Jordan

Lebanon

Syria

Türkiye

Bulgaria

Serbia

Croatia

Hungary

Austria

Slovakia

Poland

Belarus

Ukraine

Moldova

Romania

Georgia

Azerbaijan

Turkmenistan

Afghanistan

Pakistan

Uzbekistan

Kazakhstan

Chelyabinsk

Казань

Москва

Warsaw

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Istanbul

Ankara

Athens

Αθήνα

Algiers

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Tunis

تونس

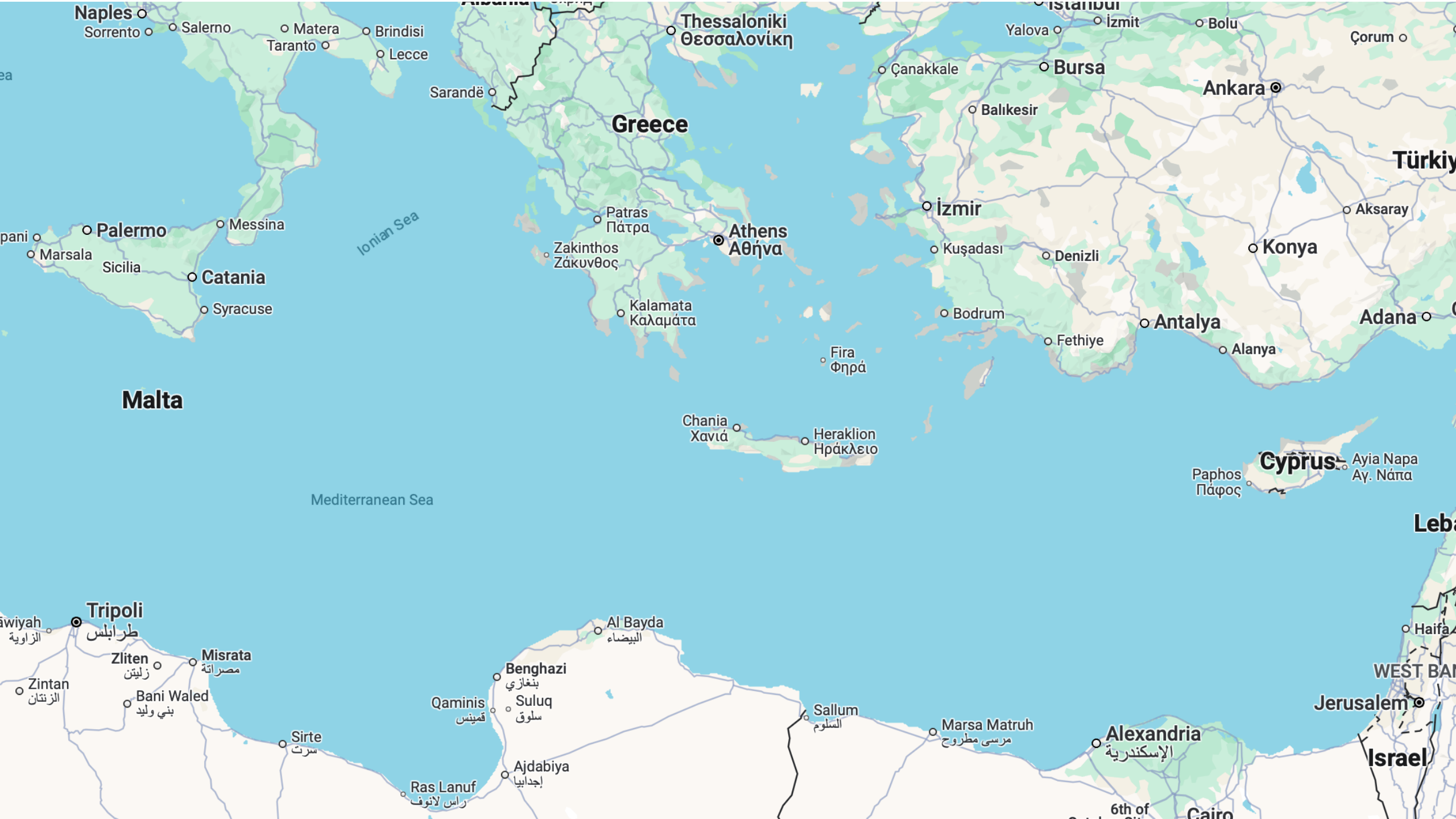
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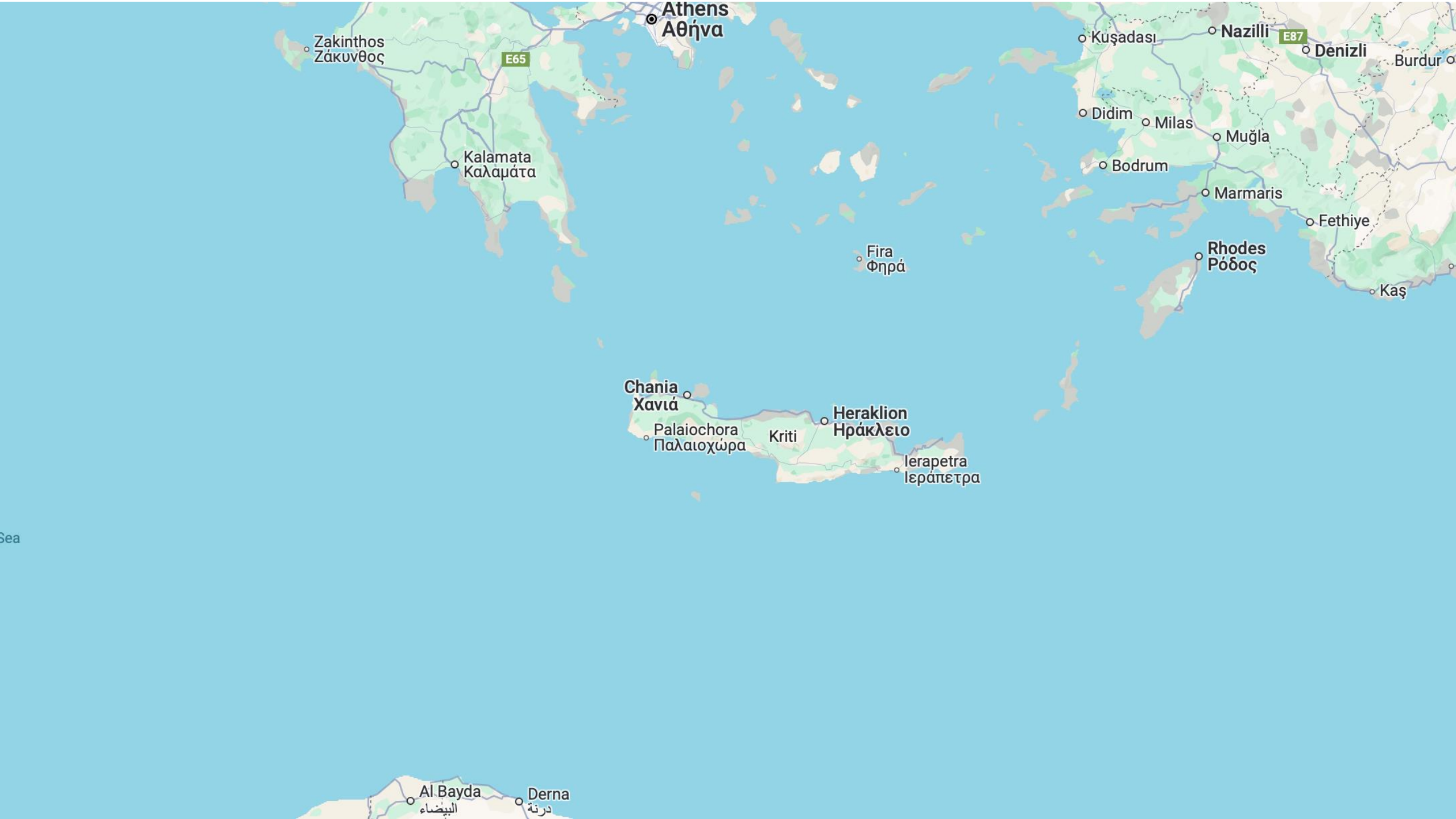
جدة

Tehran

تهران







Zakinthos
Ζάκυνθος

E65

Athens
Αθήνα

Kalamata
Καλαμάτα

Fira
Φηρά

Chania
Χανιά

Palaiochora
Παλαιοχώρα

Kriti

Heraklion
Ηράκλειο

Ierapetra
Ιεράπετρα

Rhodes
Ρόδος

Kuşadası

Nazilli

E87

Denizli

Burdur

Didim

Milas

Muğla

Bodrum

Marmaris

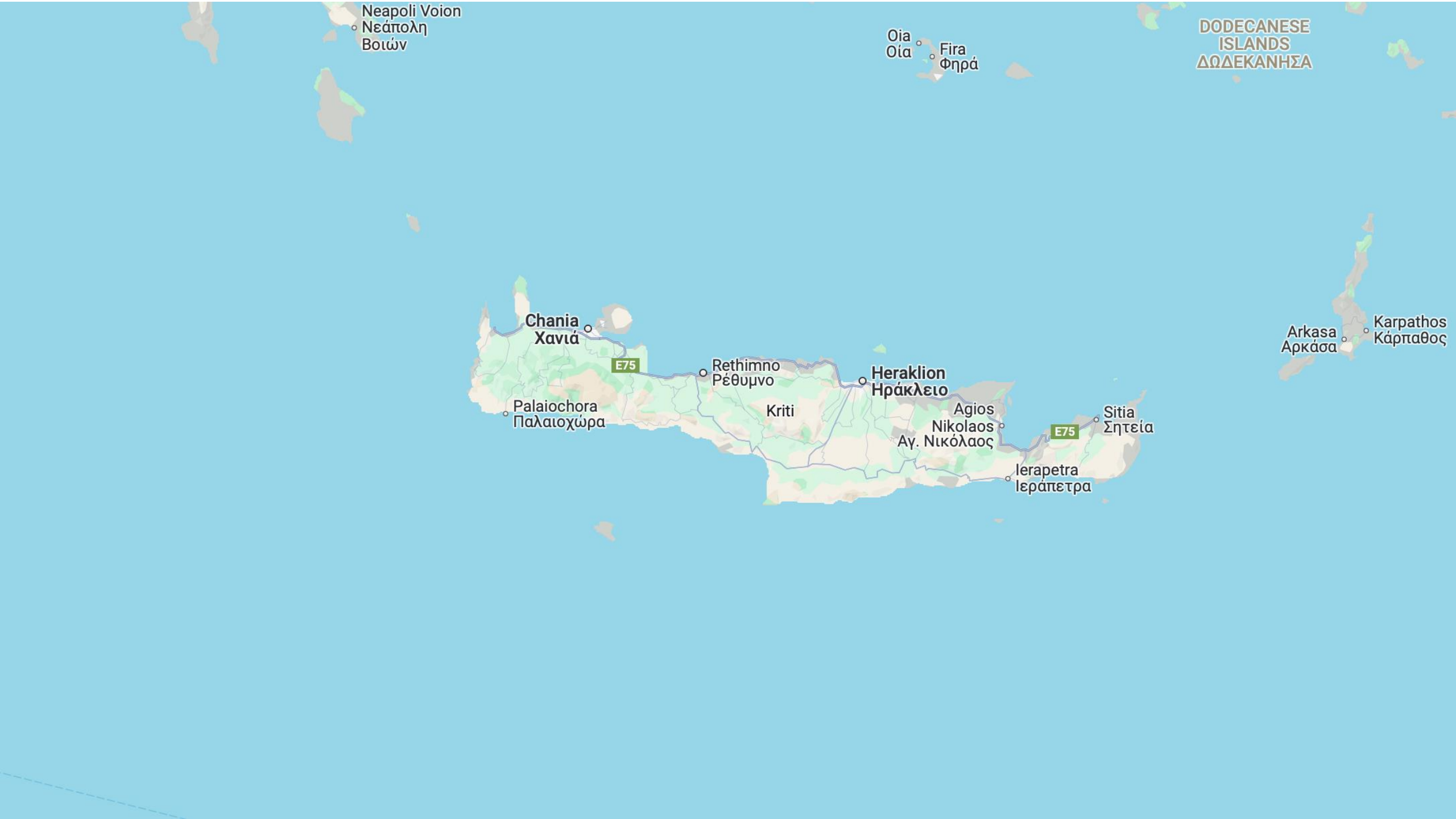
Fethiye

Kaş

Sea

Al Bayda
البيضاء

Derna
درنة



Νεαπολι
Νεάπολη
Βοιών

Οία
Οία
Φηρά
Φηρά

DODECANESE
ISLANDS
ΔΩΔΕΚΑΝΗΣΑ

Chania
Χανιά

Palaiochora
Παλαιοχώρα

E75

Rethimno
Ρέθυμνο

Kriti

Heraklion
Ηράκλειο

Agios
Nikolaos
Αγ. Νικόλαος

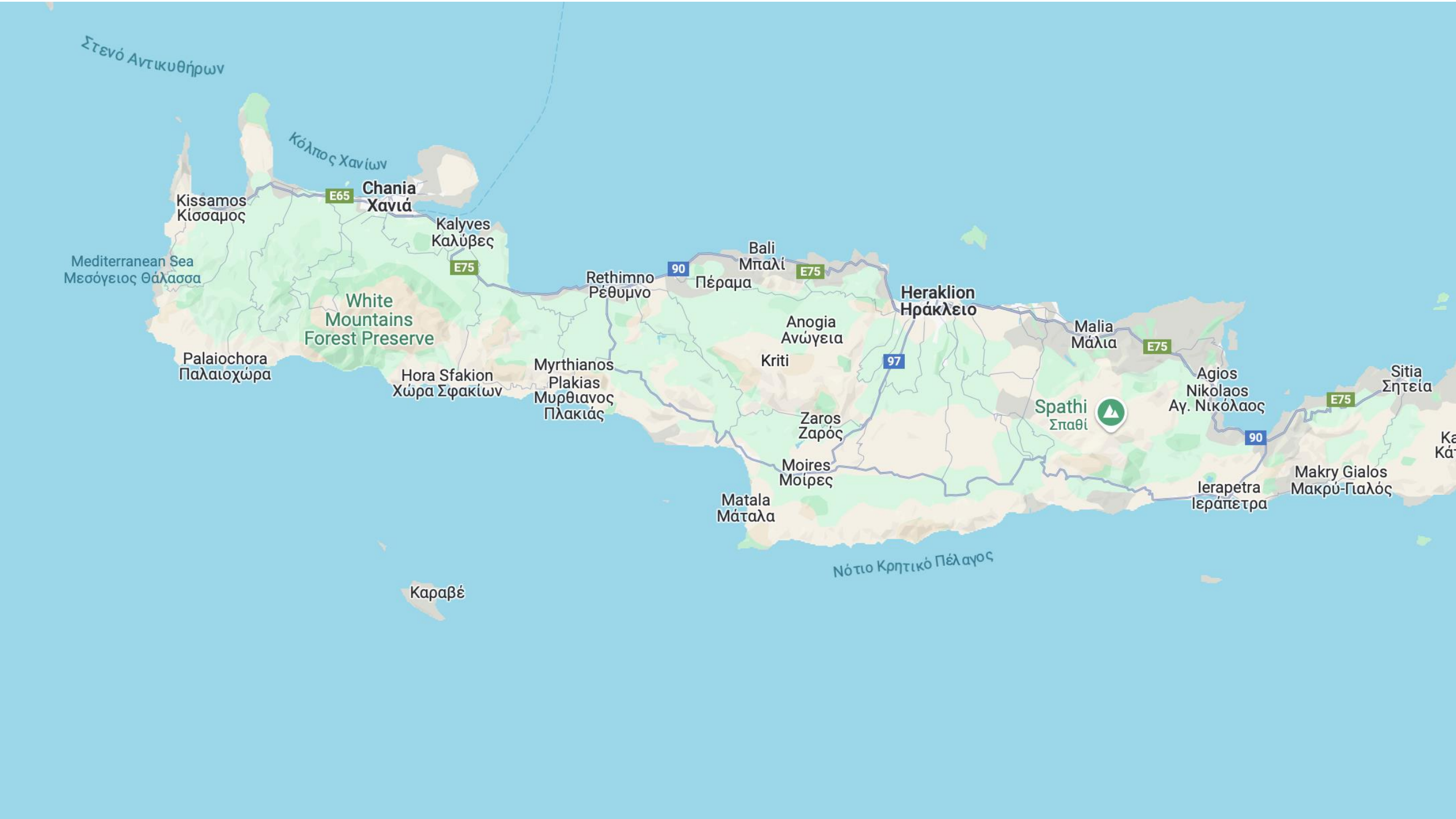
E75

Ierapetra
Ιεράπετρα

Sitia
Σητεία

Arkasa
Αρκάσα

Karpathos
Κάρπαθος



Στενό Αντικυθήρων

Κόλπος Χανίων

Kissamos
Κίσσαμος

Chania
Χανιά

Kalyves
Καλύβες

Mediterranean Sea
Μεσόγειος Θάλασσα

White
Mountains
Forest Preserve

Palaiochora
Παλαιοχώρα

Hora Sfakion
Χώρα Σφακίων

Myrthianos
Plakias
Μυρθιανός
Πλακιάς

Rethimno
Ρέθυμνο

Pherama
Πέραμα

Bali
Μπαλί

Anogia
Ανώγεια

Kriti

Zaros
Ζαρός

Moires
Μοίρες

Matala
Μάταλα

Heraklion
Ηράκλειο

Spathi
Σπαθί

Malia
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Αγ. Νικόλαος

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Ιεράπετρα

Makry Gialos
Μακρύ-Γιαλός

Sitia
Σητεία

Karabagi
Καραβέ

Νότιο Κρητικό Πέλαγος

**We are looking forward to seeing you
in Crete
6.10 – 10.10.2025**